

WHAT IS CLAIMED IS:

1. A solid state thermal apparatus comprising:
 - a heat source;
 - a heat transferring converter having an open-ended passageway;
 - a plurality of solid state devices carried on said heat transferring converter;
 - a thermal cable coupling said heat source with said diode array;
 - a thermal conductive arrangement incorporated into said heat transferring converter for conductive transfer of heat energy from said plurality of solid state devices into said open-ended passageway; and
 - blower means disposed at a selected end of said passageway forcing heat energy in said passageway through said passageway.
2. The solid state thermal apparatus defined in Claim 1 wherein:
 - said selected end of said passageway is an inlet and a non-selected end of said passageway is an exhaust exit; and
 - said blower means is disposed in said inlet with forced heat energy exhausting via said exit.
3. The solid state thermal apparatus defined in Claim 2 wherein:
 - said solid state devices include a plurality of diode arrays.

4. The solid state thermal apparatus defined in Claim 3 wherein:

said thermal conductive arrangement includes a plurality of stages indexed with each of said diode arrays for transferring heat energy to said thermal passageway.

5. The solid state thermal apparatus defined in Claim 4 wherein:

each of said thermal conductive stages is composed of a carbon graphite composition capable of conducting heat energy at least five times the rate of heat energy conduction of copper.

6. The solid state thermal apparatus defined in Claim 5 including:

a power source operably coupled to said diode arrays by a plurality of positive and negative terminals.

7. The solid state thermal apparatus defined in Claim 6 including:

a pair of conductor plates associated with each of said diode arrays connected between said pair of conductor plates; and

said positive and negative terminals connected to each of said pair of conductor plates respectively.

8. A solid state thermal apparatus which comprises:

- a heat source;
- an array of panels with each panel carrying a plurality of diodes;
- a thermal cable coupling said heat source with said array of panels;
- a heat transferring converter having an enclosure defining an open-ended passageway;
- said array of panels carried on the exterior of said heat transferring converter so as to be in heat transference relationship therewith;
- said enclosure having a plurality of heat transference stages insulated from each other; and
- each panel in said array of panels disposed immediately adjacent to a respective heat transference stage for conducting heat energy from said panels to said heat transference stages for conductive transfer of heat energy into said open-ended passageway.

9. The solid state thermal apparatus defined in Claim 8 wherein:

- said passageway includes an inlet and an outlet with a blower mounted in said inlet for forcing a flow of ambient air through said passageway for exhausting heat energy collected via said outlet.

10. The solid state thermal apparatus defined in Claim 9 wherein:

each of said heat transference stages is composed of a carbon composite material having a high rate of thermal conductivity.

11. The solid state thermal apparatus defined in Claim 10 wherein:

each of said panels includes a multiplicity of diodes for conducting heat energy thereby pulling heat energy from said heat source.

12. The solid state thermal apparatus defined in Claim 10 including:

a power source operably connected to said diodes.

13. The solid state thermal apparatus defined in Claim 12 wherein:

said thermal cable includes a plurality of parallel paths carried on a flexible cable.

14. The solid state thermal apparatus defined in Claim 13 wherein:

each of said diodes is a ceramic quartz diode; and
said graphite material is heat conductive directional.